

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shouhei KOZAKAI et al.

Application No.: 10/829,150

Confirmation No.: 5728

Filed: April 22, 2004

Art Unit: 1771

For: DICING/DIE BONDING ADHESION TAPE

Examiner: D. R. ZIRKER

AMENDMENT IN RESPONSE TO NON-FINAL OFFICE ACTION

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated July 13, 2006, please amend the above-identified U.S. patent application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.